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SOD-523

MARKING: A6



BAS16X Swithching Diode

FEATURES

- High-Speed Switching Applications
- Lead Finish: 100% Matte Sn (Tin)
- Qualified Reflow Temperature: 260 °C
- Extremely Small SOD-523 Package

MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

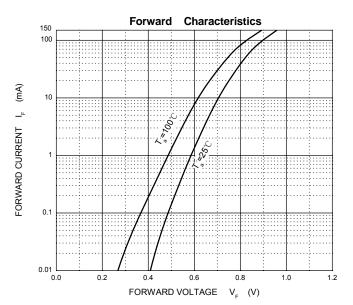
Symbol	Parameter	Value	Unit
V_{R}	Reverse Voltage	75	V
I _F	Forward Continuous Current	200	mA
I _{FSM}	Non-repetitive Peak Forward Surge Current@t=8.3ms	2	Α
P _D	Power Dissipation	150	mW
R _{OJA}	Thermal Resistance from Junction to Ambient	833	°C/W
T _j	Junction Temperature	150	℃
T _{stg}	Storage Temperature	-55~+150	℃

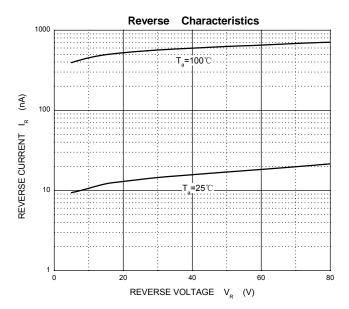
Electrical Ratings @Ta=25℃

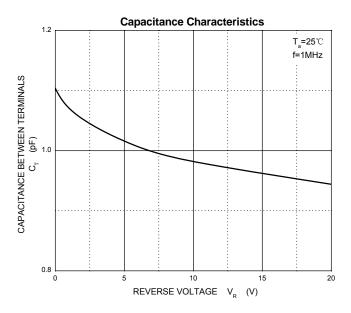
Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Reverse breakdown voltage	V _(BR)	75				I _R =100uA
	V _{F1}			715		I _F =1mA
Company voltage	V _{F2}			855	m\/	I _F =10mA
Forward voltage	V _{F3}			1000	mV	I _F =50mA
	V _{F4}			1250		I _F =150mA
Reverse recovery Time	t _{rr}			6.0	ns	$I_F=I_R=10$ mAdc, $R_L=50\Omega$
Reverse current	I _R			1.0	μА	V _R =75V
Forward recovery voltage to	V_{FR}			1.75	٧	I _F =10mA, t _r = 20ns
Diode capacitance	C _D			2.0	pF	V _R =0V,f=1MHz
Stored charge	Qs			45	рС	I _F =10mA, V _R =5.0V ,R _L =500Ω

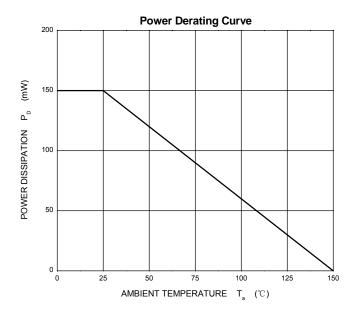


Typical Characteristics



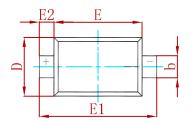


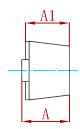


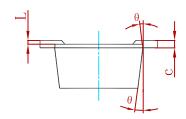




PACKAGE MECHANICAL DATA

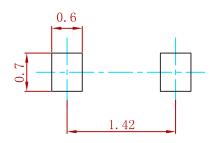






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		0.008 REF		
L	0.010	0.070	0.001	0.003	
θ	7° RFF		7° F	RFF	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

·		
P/N	PKG	QTY
BAS16X	SOD-523	3000



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